



31st IEEE WORKSHOP ON SIGNAL AND POWER INTEGRITY

MAY 16-19, 2027 - RIVA DEL GARDA, ITALY



spi-workshop.org



spi2027@polito.it

The IEEE Workshop on Signal and Power Integrity (SPI) is an annual scientific event in Europe that stands today as a premier forum of exchange on all aspects of Signal and Power Integrity, encompassing the latest research and developments on design, characterization, modeling, simulation and testing at chip, package, board, and system levels.

To continue this legacy of global collaboration, researchers and developers from academia and industry worldwide are cordially invited to submit their latest work and join us for SPI 2027, taking place as an in-person event from May 16 to 19, in the scenic lakeside town of Riva del Garda, Italy!

Full Paper Submission	Jan 8, 2027
Notification of Acceptance	Feb 1, 2027
Final Paper Submission	Mar 1, 2027
Early Bird Registration	Mar 1, 2027
Sponsors Registration	Mar 1, 2027

SPI 2027 AWARDS & GRANTS

Best Paper Award | Best Student Paper Award | IEEE EPS Student Travel Grants

Workshop Chair

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University of Brest (FRA)
Dries Vande Ginste
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CALL FOR PAPERS

Original and unpublished contributions are welcomed, related to the following TOPICS of interest:

- Modeling and simulation for SI/PI
- Coupled signal and power integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-on-chip
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects
- AI in electronics design

